CBT3245A

Octal bus switch

Rev. 3 — 5 January 2012 Product data sheet

1. General description

The CBT3245A provides eight bits of high-speed TTL-compatible bus switching. The low ON resistance of the switch allows connections to be made with minimal propagation delay.

The CBT3245A is organized as one 8-bit bus switches with one output enable ($\overline{OE}$) input. When $\overline{OE}$ is LOW, the switch is on and port A is connected to the B port. When $\overline{OE}$ is HIGH, each switch is disabled. The CBT3245A is characterized for operation from −40 °C to +85 °C.

2. Features and benefits

- 5 Ω switch connection between two ports
- TTL-compatible control input levels
- Multiple package options
- Latch-up protection exceeds 500 mA per JESD78
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115B exceeds 150 V
  - CDM JESD22-C101C exceeds 1000 V

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
CBT3245AD	−40 °C to +85 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
CBT3245ADB	−40 °C to +85 °C	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
CBT3245ADS	−40 °C to +85 °C	SSOP20[1]	plastic shrink small outline package; 20 leads; body width 3.9 mm; lead pitch 0.635 mm	SOT724-1
CBT3245APW	−40 °C to +85 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
CBT3245ABQ	−40 °C to +85 °C	DHVQFN20	plastic dual-in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

[1] Also known as QSOP20 package

4. Functional diagram

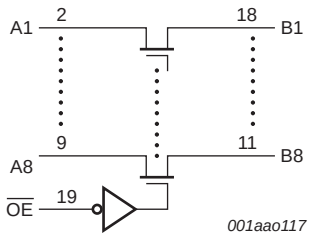


Fig 1. Logic diagram

5. Pinning information

5.1 Pinning

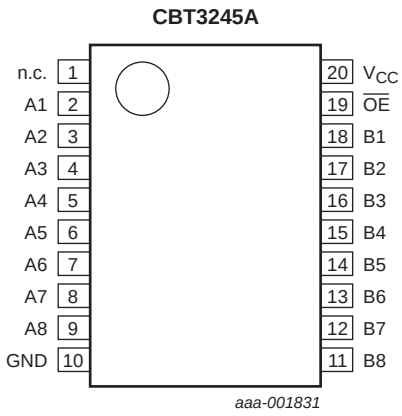


Fig 2. Pin configuration for SOT163-1 (SO20), SOT339-1 (SSOP20) and SOT360-1 (TSSOP20)

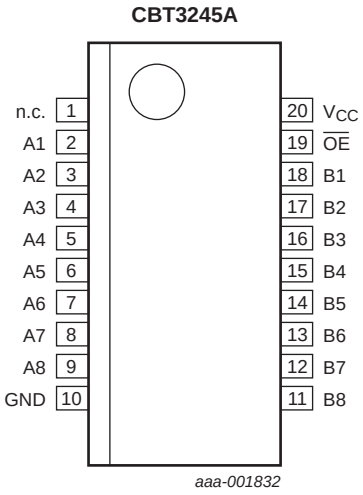
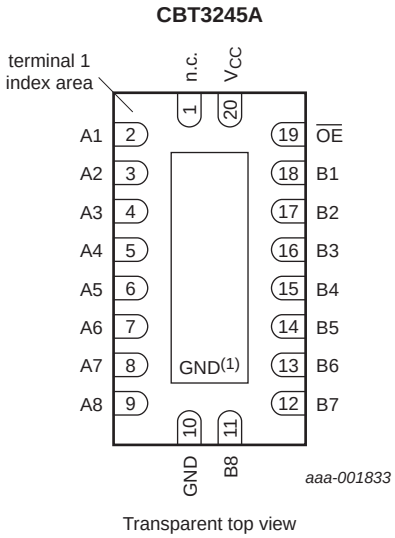


Fig 3. Pin configuration for SOT724-1 (SSOP20)



Transparent top view

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 4. Pin configuration for SOT764-1 (DHVQFN20)

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
n.c.	1	not connected
A1 to A8	2, 3, 4, 5, 6, 7, 8, 9	data input/output (A port)
GND	10	ground (0 V)
B1 to B8	18, 17, 16, 15, 14, 13, 12, 11	data input/output (B port)
$\overline{OE}$	19	output enable input (active LOW)
V_{CC}	20	positive supply voltage

6. Functional description

Table 3. Function selection[1]

Input	Input/output
$\overline{OE}$	**An, Bn**
L	An = Bn
H	Z

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]
T_{amb} = –40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			–0.5	+7.0	V
V_I	input voltage		[2]	–0.5	+7.0	V
I_{OK}	output clamping current	V_O < 0 V		–50	-	mA
V_O	output voltage		[2]	–0.5	+7.0	V
I_O	output current	V_O < 0 V		-	±128	mA
I_{IK}	input clamping current	V_I = 0 V		–50	-	mA
T_{stg}	storage temperature			–65	+150	°C

[1] Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under Section 8. is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[2] The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

8. Recommended operating conditions

Table 5. Operating conditions

All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		4.0	-	5.5	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.8	V
T_{amb}	ambient temperature	operating in free air	–40	-	+85	°C

9. Static characteristics

Table 6. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		T_{amb} = –40 °C to +85 °C			Unit
				Min	Typ[1]	Max	
V_{IK}	input clamping voltage	V_{CC} = 4.5 V; I_I = –18 mA		-	-	–1.2	V
I_I	input leakage current	V_{CC} = 5.5 V; V_I = GND or 5.5 V		-	-	±5	µA
I_{CC}	supply current	V_{CC} = 5.5 V; I_O = 0 mA; V_I = V_{CC} or GND		-	1	3	µA
ΔI_{CC}	additional supply current	per input pin; V_{CC} = 5.5 V; one input at 3.4 V, other inputs at V_{CC} or GND	[2]	-	-	3.5	mA
C_I	input capacitance	control pins; V_I = 3 V or 0 V		-	3.2	-	pF
$C_{io(off)}$	off-state input/output capacitance	port off; V_I = 3 V or 0 V; $\overline{OE}$ = V_{CC}		-	6.6	-	pF

Table 6. Static characteristics *…continued*

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		T_{amb} = –40 °C to +85 °C			Unit
				Min	Typ[1]	Max	
R_{ON}	ON resistance	V_{CC} = 4.5 V; V_I = 0 V; I_I = 64 mA	[3]	-	5	7	Ω
		V_{CC} = 4.5 V; V_I = 0 V; I_I = 30 mA	[3]	-	5	7	Ω
		V_{CC} = 4.5 V; V_I = 2.4 V; I_I = –15 mA	[3]	-	10	15	Ω

[1] All typical values are at V_{CC} = 5 V, T_{amb} = 25 °C.

[2] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[3] Measured by the voltage drop between the An and the Bn terminals at the indicated current through the switch. ON resistance is determined by the lowest voltage of the two (An or Bn) terminals.

10. Dynamic characteristics

Table 7. Dynamic characteristics

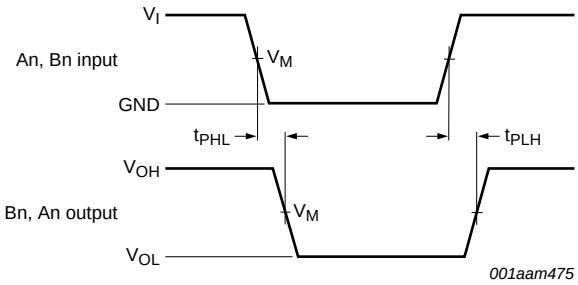
Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 7.

Symbol	Parameter	Conditions		T_{amb} = –40 °C to +85 °C		Unit
				Min	Max	
t_{pd}	propagation delay	An, Bn to Bn, An; see Figure 5	[1][2]			
		V_{CC} = 5.0 V ± 0.5 V		-	0.25	ns
t_{en}	enable time	$\overline{OE}$ to An or Bn; see Figure 6	[2]			
		V_{CC} = 5.0 V ± 0.5 V		1.0	5.9	ns
t_{dis}	disable time	$\overline{OE}$ to An or Bn; see Figure 6	[2]			
		V_{CC} = 5.0 V ± 0.5 V		1.0	6.0	ns

[1] The propagation delay is the calculated RC time constant of the typical ON resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{PZL} and t_{PZH}.
t_{dis} is the same as t_{PLZ} and t_{PHZ}.

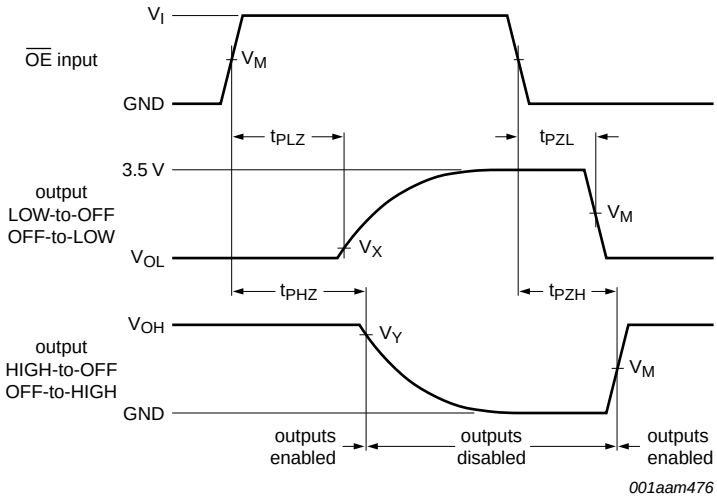
11. Waveforms



Measurement points are given in Table 8.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 5. The data input (An, Bn) to output (Bn, An) propagation delay times



Measurement points are given in Table 8.

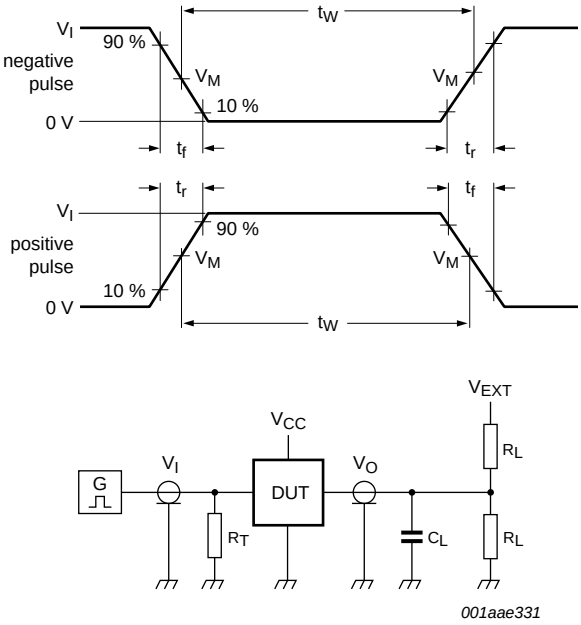
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 6. Enable and disable times

Table 8. Measurement points

Supply voltage	Input		Output		
V_{CC}	V_I	V_M	V_M	V_X	V_Y
V_{CC} = 5.0 V ± 0.5 V	GND to 3.0 V	1.5 V	1.5 V	V_{OL} + 0.3 V	V_{OH} − 0.3 V

12. Test information



Test data is given in Table 9.

All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz; Z_o = 50 Ω.

The outputs are measured one at a time with one transition per measurement.

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

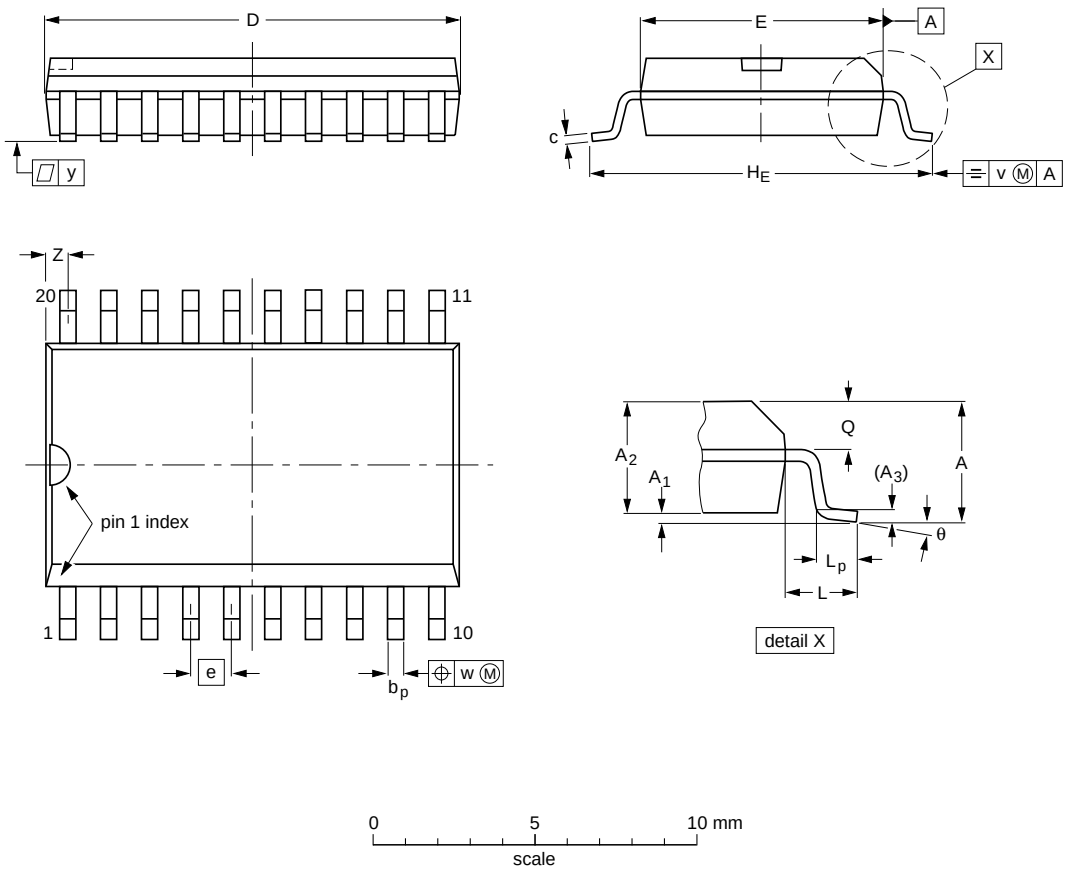
Fig 7. Test circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
V_{CC} = 5.0 V ± 0.5 V	GND to 3.0 V	≤ 2.5 ns	50 pF	500 Ω	open	7.0 V	open

13. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

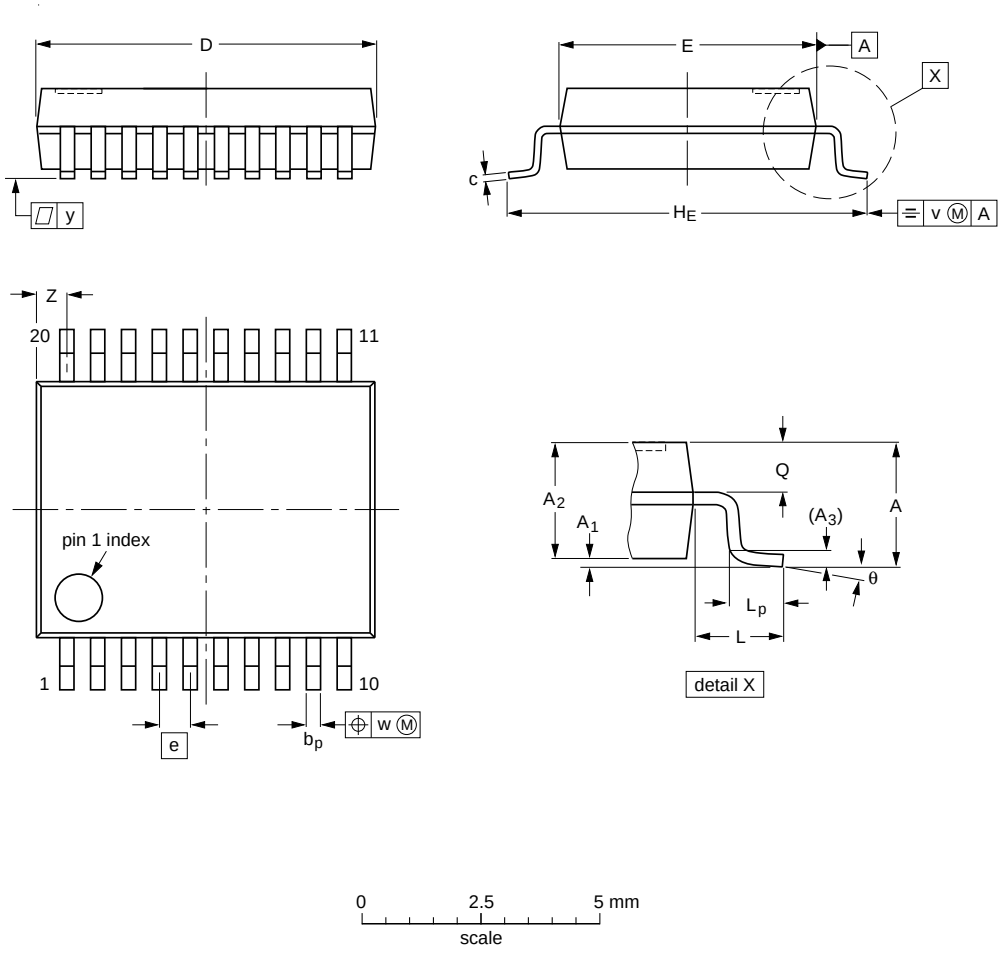
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 8. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm **SOT339-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8^o 0^o

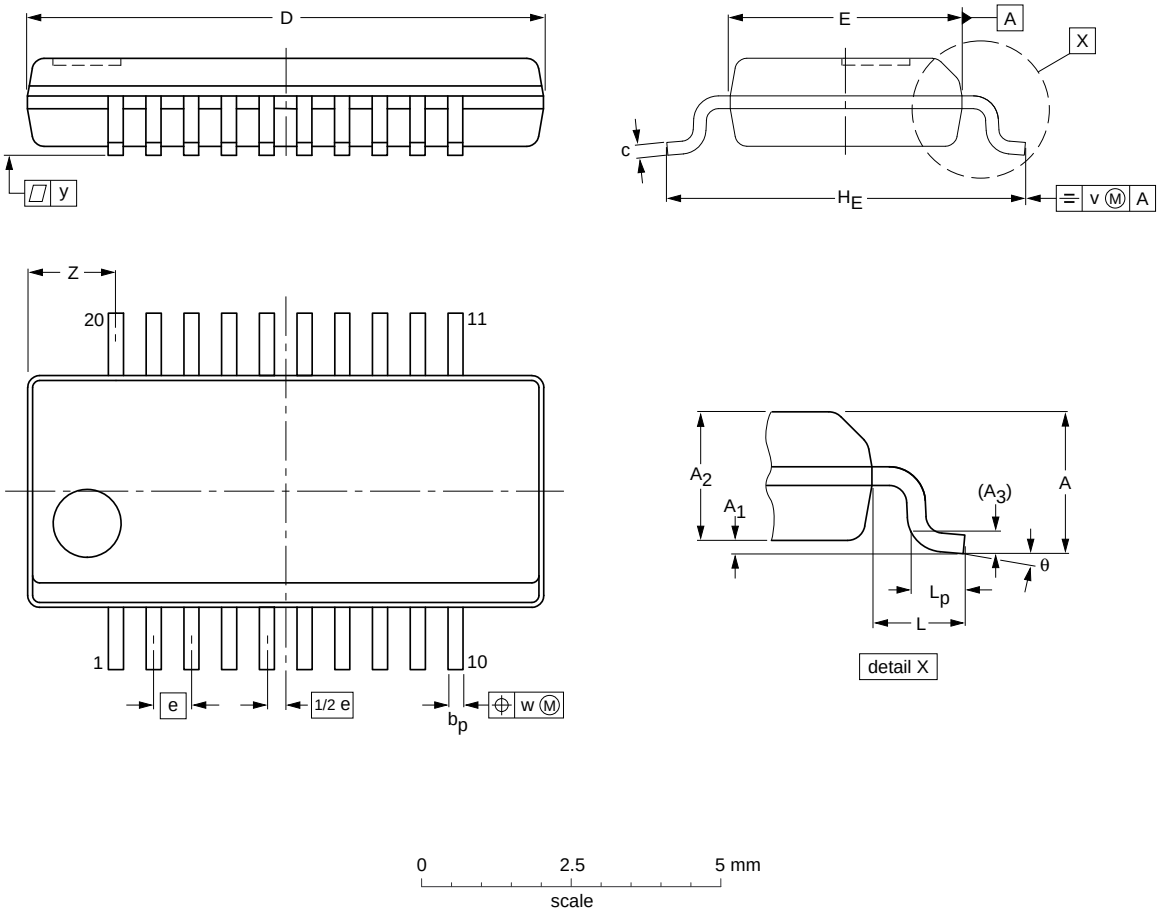
Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT339-1		MO-150				~~99-12-27~~ 03-02-19

Fig 9. Package outline SOT339-1 (SSOP20)

SSOP20: plastic shrink small outline package; 20 leads; body width 3.9 mm; lead pitch 0.635 mm SOT724-1



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	v	w	y	$Z^{(1)}$	θ
mm	1.73	0.25 0.10	1.55 1.40	0.25	0.31 0.20	0.25 0.18	8.8 8.6	4.0 3.8	0.635	6.2 5.8	1	0.89 0.41	0.25	0.18	0.1	1.67 1.28	8^o 0^o

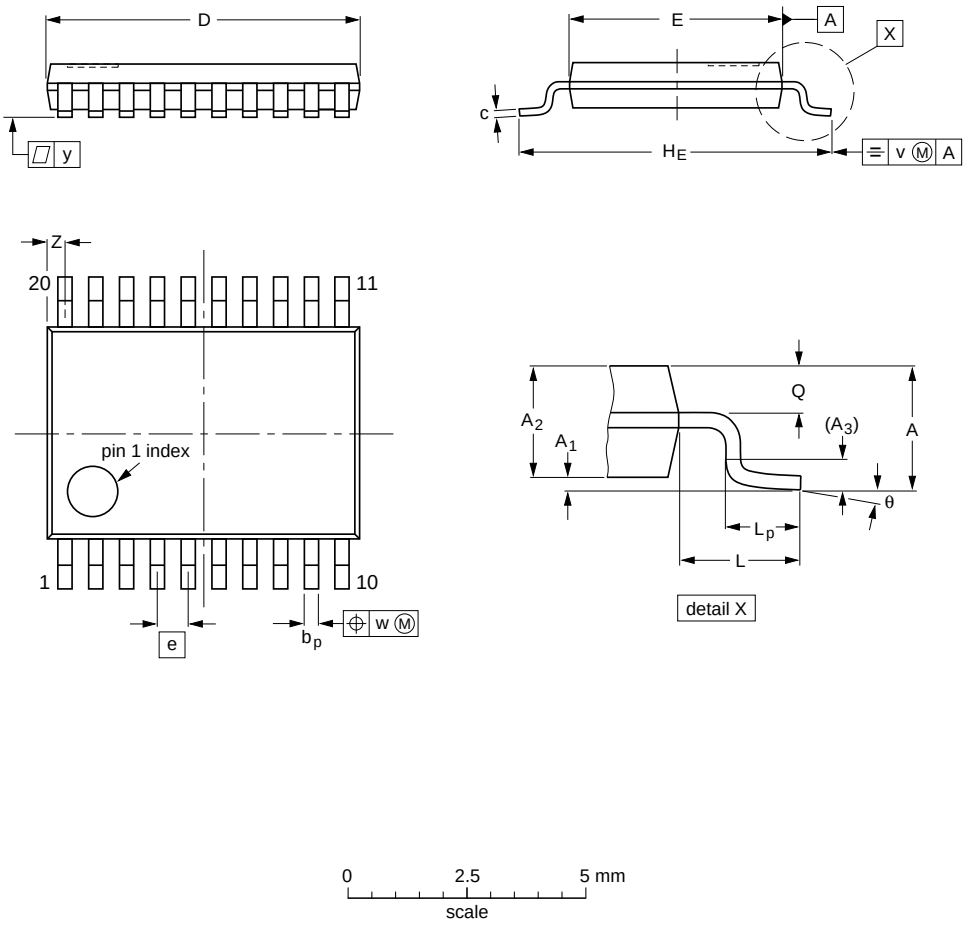
Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT724-1		MO-137				~~01-07-04~~ 03-02-18

Fig 10. Package outline SOT724-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8^o 0^o

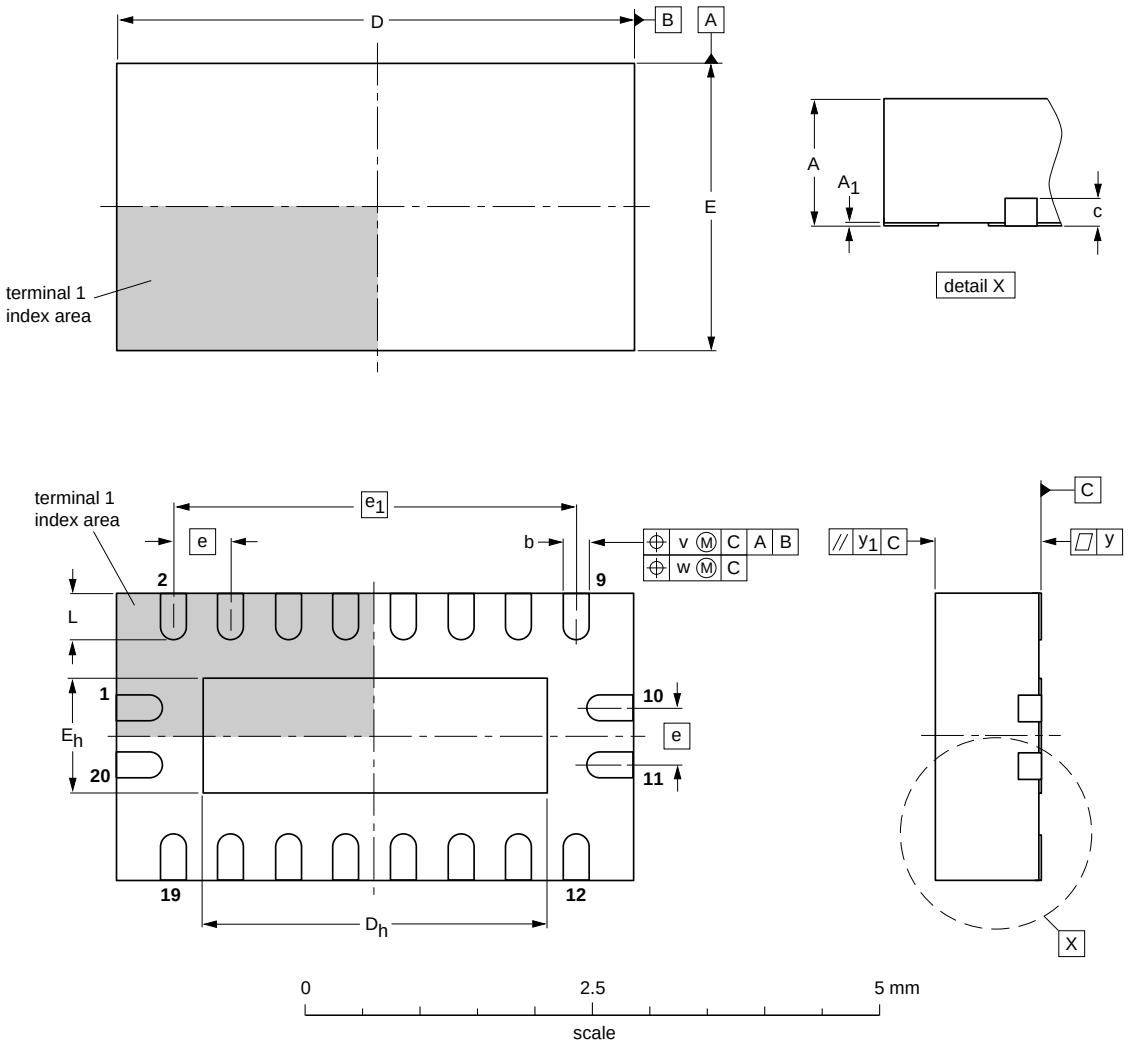
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 11. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm **SOT764-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	A_1	b	c	D(1)	D_h	E(1)	E_h	e	e_1	L	v	w	y	y_1
mm	1	0.05 0.00	0.30 0.18	0.2	4.6 4.4	3.15 2.85	2.6 2.4	1.15 0.85	0.5	3.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT764-1	- - -	MO-241	- - -			~~02-10-17~~ 03-01-27

Fig 12. Package outline SOT764-1 (DHVQFN20)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
ESD	ElectroStatic Discharge
DUT	Device Under Test
HBM	Human Body Model
MM	Machine Model
PRR	Pulse Rate Repetition
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
CBT3245A v.3	20120105	Product data sheet	-	CBT3245A v.2
Modifications:	• The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Marking code removed from order information section. • Description of C_I and $C_{I/O}$ corrected (errata).			
CBT3245A v.2	20020627	Product data sheet	-	CBT3245A v.1
CBT3245A v.1	20020218	Product data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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16.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

17. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

18. Contents

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